TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

## TD62783AP,TD62783F,TD62783AF TD62784AP,TD62784F,TD62784AF

#### 8CH HIGH-VOLTAGE SOURCE DRIVER

The TD62783AP / F / AF Series are comprised of eight source current Transistor Array.

These drivers are specifically designed for fluorescent display applications.

Applications include relay, hammer and lamp drivers.

#### **FEATURES**

• High output voltage Type-AP, AF :  $V_{CC} = 50 \text{ V MIN}$ . Type-F :  $V_{CC} = 35 \text{ V MIN}$ .

• Output current (single output) IOUT = -500 mA MIN.

Output clamp diodes

Single supply voltage

Input compatible with various types of logic

Package Type-AP : DIP-18 pinPackage Type-F, AF : SOP-18 pin

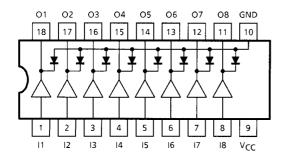
TYPE	DESIGNATION			
TD62783AP / F / AF	TTL, 5 V CMOS			
TD62784AP / F / AF	6~15 V PMOS, CMOS			

# TD62783AP TD62784AP DIP18-P-300-2.54D TD62783F TD62783AF TD62784AF TD62784AF TD62784AF

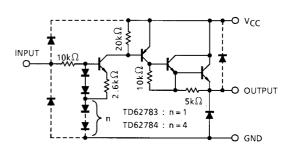
Weight

DIP18-P-300-2.54D : 1.47 g (Typ.) SOP18-P-375-1.27 : 0.41 g (Typ.)

## **PIN CONNECTION (TOP VIEW)**



#### **SCHEMATICS (EACH DRIVER)**



Note: The input and output parasitic diodes cannot be used as clamp diodes.



## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT		
Supply Voltage	AP, AF	V <sub>CC</sub>	50	V	
Supply Voltage	F	vCC	35	V	
Output Current		lout	-500	mA / ch	
Input Voltage	V <sub>IN</sub> (Note 1)	15	V		
Input Voltage		V <sub>IN</sub> (Note 2)			30
Clamp Diode Reverse	AP, AF	V <sub>R</sub>	50	V	
Voltage	F	VR	35	V	
Clamp Diode Forward Curre	lF	500	mA		
Power Dissipation	AP	P <sub>D</sub> (Note 3)	1.47	W	
Fower Dissipation	F, AF	FD (Note 3)	0.96	VV	
Operating Temperature	T <sub>opr</sub>	-40~85	°C		
Storage Temperature	T <sub>stg</sub>	-55~150	°C		

Note 1: Only TD62783AP / F / AF Note 2: Only TD62784AP / F / AF

Note 3: Delated above 25°C in the proportion of 11.7 W / °C (AP Type), 7.7 W / °C (F, AF Type)

## RECOMMENDED OPERATING CONDITIONS (Ta = $-40 \sim 85$ °C)

CHARACTERISTIC			SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT	
Supply Voltage AP, AF		V	_		_	_	50	V		
Supply Voltage F			F	V <sub>CC</sub>	_		-	_	35	V
Output Current				Ta = 85°C	Duty = 10% 8Circuits	_	_	-260	mA /	
					Duty = 50% 8Circuits	_	_	-59		
			lout	$T_j = 120$ °C $T_{pw} = 25$ ms	Duty = 10% 8Circuits	_	_	-180	ch	
			AF, F			Duty = 50% 8Circuits	_	_		-38
Input Voltage		/ F / AF	- V <sub>IN</sub>	_		_	_	12	V	
		/ F / AF		_		-	_	24		
	Output	TD62783AP	/ F / AF	V	_		2.0	5.0	15	V
Input	On	TD62784AP	/ F / AF	V <sub>IN</sub> (ON)	_		4.5	12.0	30	
Voltage	Output	TD62783AP	/F/AF	V	_		0	_	0.8	
	Off	TD62784AP	/ F / AF	V <sub>IN</sub> (OFF)	_		0	_	2.0	
Clamp Diode Reverse AP Voltage F, AF		\/_	_		-	_	50	V		
		$V_{R}$	_		_	_	35	· I		
Clamp Diode Forward Current			IF	_		_	_	400	mA	
Power Dissipation AP F, AF		D-	_		_	_	0.52	W		
		F, AF	P <sub>D</sub>	_			_	0.35	VV	



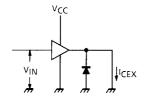
# **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARACTERISTIC			SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage Current		I <sub>CEX</sub>	1	V <sub>CC</sub> = V <sub>CC MAX</sub> . V <sub>IN</sub> = 0.4 V Ta = 25°C	_	_	100	μA	
Output Saturation Voltage			2	$V_{IN} = V_{IN (ON)},$ $I_{OUT} = -350 \text{ mA}$	-	_	2.0	V	
		V <sub>CE</sub> (sat)		$V_{IN} = V_{IN (ON)},$ $I_{OUT} = -225 \text{ mA}$	-	_	1.9		
				V <sub>IN</sub> = V <sub>IN</sub> (ON), I <sub>OUT</sub> = -100 mA	-	_	1.8		
	TD62783AP / F / AF		- In (On)	3	V <sub>IN</sub> = 2.4 V	_	36	52	μΑ
Input Current					V <sub>IN</sub> = 3.85 V	_	180	260	
	TD62784AP / F / AF				V <sub>IN</sub> = 5 V	_	92	130	
					V <sub>IN</sub> = 12 V	_	790	1130	
	TD62783A	TD62783AP / F / AF		4	V <sub>CE</sub> = 2.0 V	_	_	2.0	
Input	TD62784AP / F / AF		V <sub>IN</sub> (ON)		I <sub>OUT</sub> = −350 mA	_	_	4.5	v
Voltage	TD62783AP / F / AF		V		- 500 ·· A	0.8	_	_	V
	TD62784A	P/F/AF	V <sub>IN (OFF)</sub>		I <sub>OUT</sub> = -500 μA	2.0	_	_	
Supply Current		ICC (ON)	3	V <sub>IN</sub> = V <sub>IN (ON)</sub> , V <sub>CC</sub> = 50 V	_	_	2.5	mA / ch	
Clamp Diode AP, AF			5	V <sub>R</sub> = 50 V	_	_	50		
Reverse Cu	Reverse Current F		I <sub>R</sub>	5	V <sub>R</sub> = 35 V	_	_	50	μA
Clamp Diode Forward Voltage		V <sub>F</sub>	6	I <sub>F</sub> = 350 mA	_	_	2.0	V	
Turn-On Delay		t <sub>ON</sub>	7	V <sub>CC</sub> = V <sub>CC MAX.</sub> R <sub>L</sub> = 125 Ω	_	0.15	_		
Turn-Off D	Turn-Off Delay		t <sub>OFF</sub>	1 ′	$C_L = 15 \text{ pF}, R_L = 88 \Omega \text{ (F)}$	_	1.8	_	μs

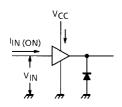
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#### **TEST CIRCUIT**

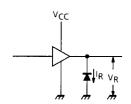
#### 1. ICEX



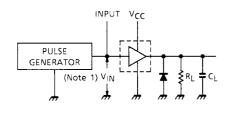
## 3. I<sub>IN (ON)</sub>, I<sub>CC</sub>



### 5. I<sub>R</sub>



## 7. ton, toff

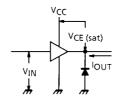


Note 1: Pulse width 50  $\mu s,\,duty$  cycle 10%

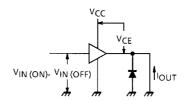
Output impedance 50  $\Omega$ ,  $t_r \le 5$  ns,  $t_f \le 10$  ns

Note 2: C<sub>L</sub> includes probe and jig capacitance

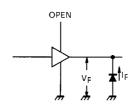
## 2. VCE (sat)

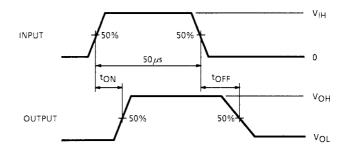


## 4. V<sub>IN (ON)</sub>, V<sub>IN (OFF)</sub>



## 6. V<sub>F</sub>



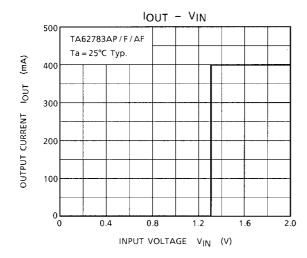


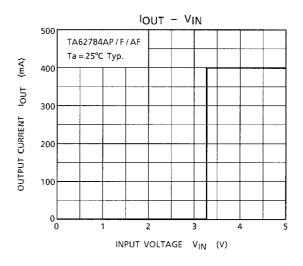
#### PRECAUTIONS for USING

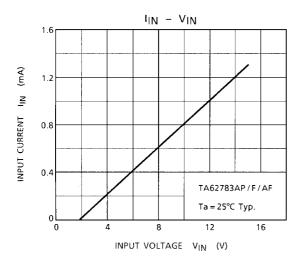
This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

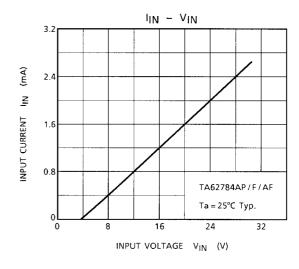
Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

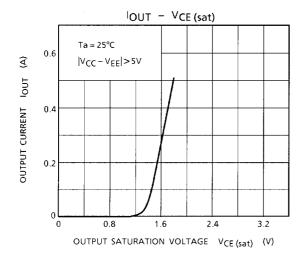
Utmost care is necessary in the design of the output line,  $V_{CC}$  and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

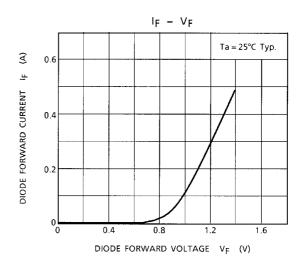


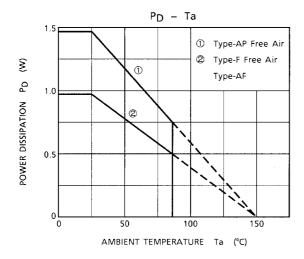










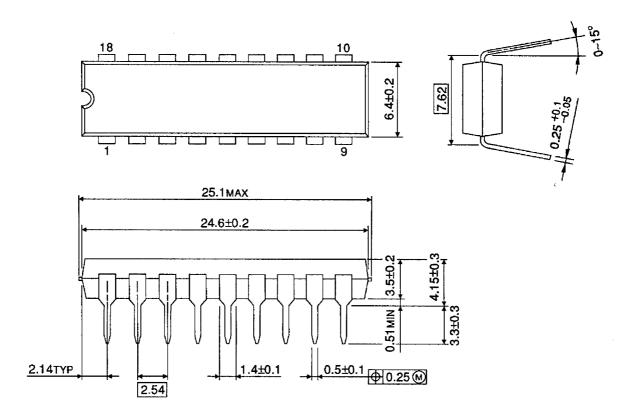


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## **PACKAGE DIMENSIONS**

DIP18-P-300-2.54D

Unit: mm



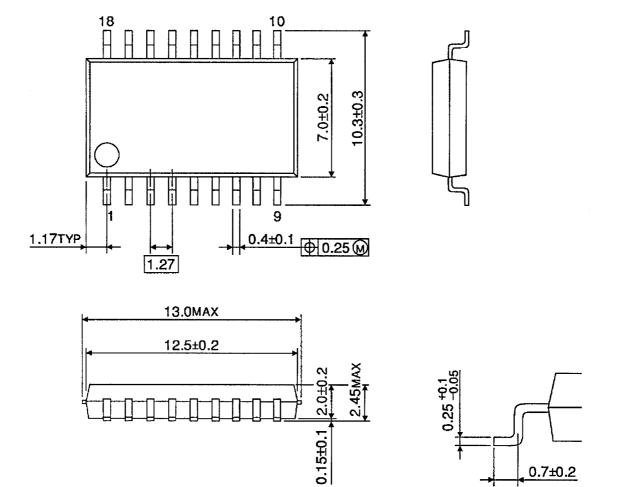
Weight: 1.47 g (Typ.)

## **PACKAGE DIMENSIONS**

SOP18-P-375-1.27

Unit: mm

0.7±0.2



Weight: 0.41 g (Typ.)

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000707EBA

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